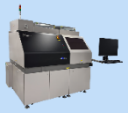
Advanced Packaging Solutions

Purpose	STI offers wide range of Advanced 2D and 3D metrology solutions for advanced packages including CMOS Sensors, 5G Mobile, Package on Package, Antenna in Package, Through Mold Via, Fan-out, 3D Stacked among others
Technology	1. **Color Inspection** – High resolution color images are captured and processed to detect defects like discoloration or exposed Copper on EMI shielded packages, Bond pad defects 2. **3D Metrology** – Multitude of 3D metrology requirements comprising Component thickness, Chiplet assembly quality, TMV via hole measurement, Wearable component's 3d profile/shape measurements are among many 3. **Large Form Factor Metrology** – Capable of performing 2D and 3D measurements applicable for Top, Bottom and Sides of package up to 120x120mm (130 x 150mm for tScan) 4. **Side Wall Inspection** – Offers component's side wall inspection with the following configurations – Visual, IR or Color Inspection.

STI Products	Color Inspection	3D Metrology	Large Form Factor Metrology	Side Wall
 **iFocus – Wafer 2D & 3D Scan**	✓	✓	✓	
 **Hexa – Tray 2D & 3D Scan**	✓	✓	✓	✓
 **tSort - WLP Scan & Sort**	✓			✓
 **tScan – 2D & 3D High Speed Scan-Pack**	✓	✓	✓	✓